TAI-SAW TECHNOLOGY CO., LTD.

Crystal Unit SMD 3.2x2.5 32.00MHz

MODEL NO.: TZ2623B REV. NO.: 1

Revise:

Rev.	Rev. Page	Rev. Account	Date	Ref. No.	Revised by
1	N/A	Initial release	10/24/14’	N/A	Derick Lin

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Crystal Unit SMD 3.2x2.5 32.00MHz

MODEL NO.: TZ2623B REV. NO.: 1

Features:

RoHS Compliant
Lead free
Lead-free soldering

- Surface Mount Hermetic Package
- Excellent Reliability Performance
- Good Frequency Perturbation and Stability over temperature
- Ultra Miniature Package

Description and Applications:

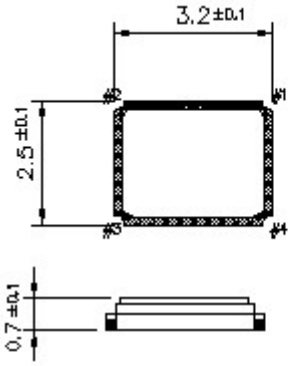
Surface mount 3.2mmx2.5mm crystal unit for customer for use in wireless communications devices, especially for a need of ultra miniature package for mobility.

Electrical Specifications:

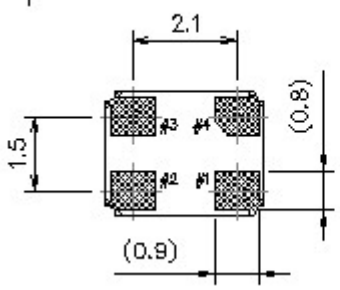
TZ2623B	**Specification**
Nominal Frequency	32.000000 MHz
Mode of Oscillation	Fundamental
Storage Temperature Range	-55°C to +125°C
Operating Temperature Range	-20°C to +70°C
Frequency Stability over Operating Temperature	+/- 10 ppm (referred to the value at 25°C)
Frequency Make Tolerance (FL)	+/- 10 ppm @ 25°C +/- 3°C
Equivalent Series Resistance (ESR)	60 Ω max.
Nominal Drive Level	10uW typical and 100uW max
Shunt Capacitance (Co)	3.0 pF max
Load Capacitance (CL)	10 pF
Insulation Resistance	500 MΩ min./DC 100V
Marking	Laser Marking
Unit Weight	0.017+/-0.005 g

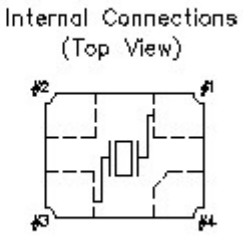
Mechanical Dimensions (mm):

Base 1

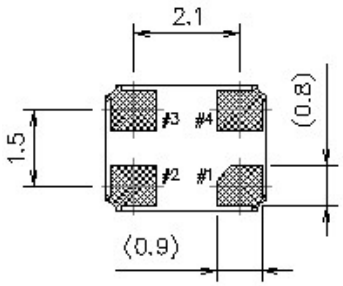


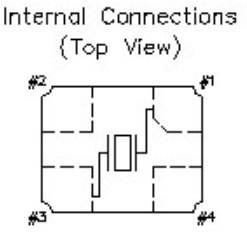
	Pin Connection
#1 pin	IN/OUT
#2 pin	GND
#3 pin	IN/OUT
#4 pin	GND



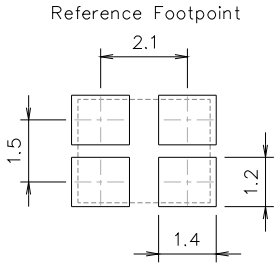


Base 2





Recommended Land Pattern: (unit: mm)



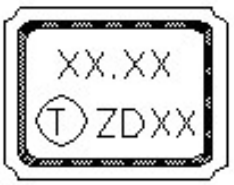
Marking:

Line 1: Frequency (32.00)

Line 2: TST Logo + Crystal Product Code + Date Code + Traceability code (1 or 2 letters)

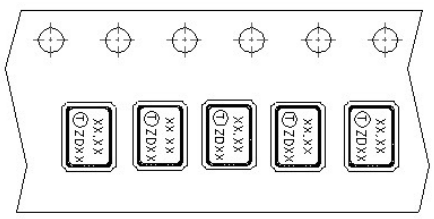
Pin#2

Pin#3



Pin#1

Pin#4



The inner vision of Pin#1, Pin#4 side is XTAL blank mounting pad.

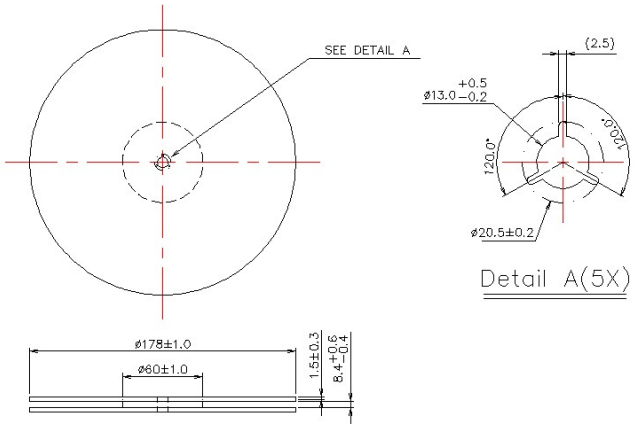
Product Code Table

Year	2009	2010	2011	2012
	2013	2014	2015	2016
	2017	2018	2019	2020
product code	Z	z	Z	z

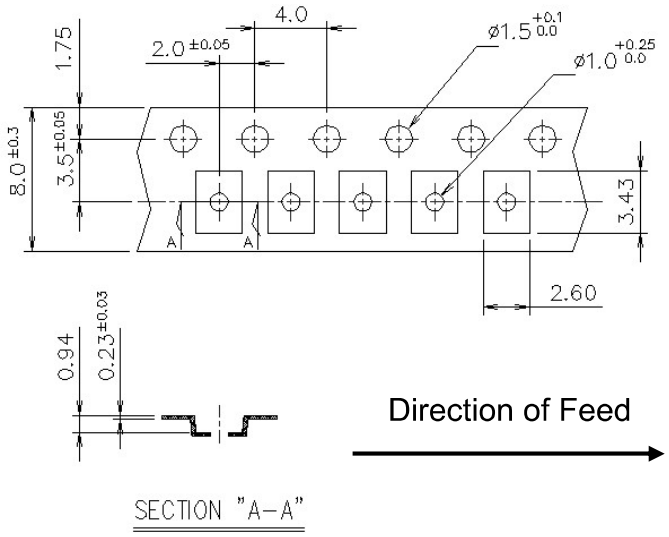
Date Code Table

WK01	WK02	WK03	WK04	WK05	WK06	WK07	WK08	WK09	WK10	WK11	WK12	WK13
A	B	C	D	E	F	G	H	I	J	K	L	M
WK14	**WK15**	**WK16**	**WK17**	**WK18**	**WK19**	**WK20**	**WK21**	**WK22**	**WK23**	**WK24**	**WK25**	**WK26**
N	O	P	Q	R	S	T	U	V	W	X	Y	Z
WK27	**WK28**	**WK29**	**WK30**	**WK31**	**WK32**	**WK33**	**WK34**	**WK35**	**WK36**	**WK37**	**WK38**	**WK39**
a	b	c	d	e	f	g	h	i	j	k	l	m
WK40	**WK41**	**WK42**	**WK43**	**WK44**	**WK45**	**WK46**	**WK47**	**WK48**	**WK49**	**WK50**	**WK51**	**WK52**
n	o	p	q	r	s	t	u	v	w	x	y	z

Reel Dimensions (mm):



Tape Dimensions (mm):



[NOTE]

1 UNIT : mm.

2 UNLESS OTHERWISE SPECIFIED TOLERANCEON DIM. +/-0.1mm.

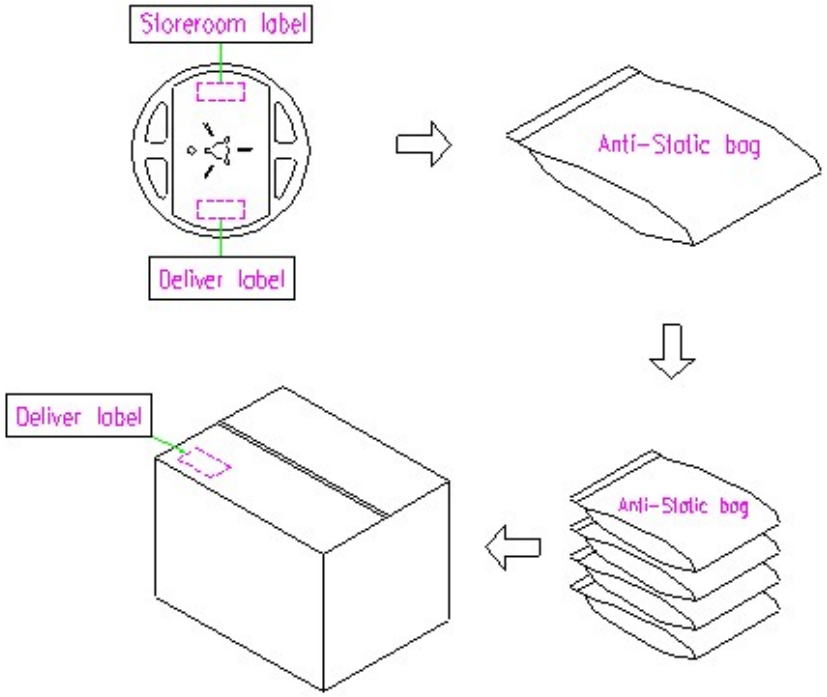
3 MATERIAL : CONDUCTIVE POLYSTYRENE.

4 COLOR : BLACK.

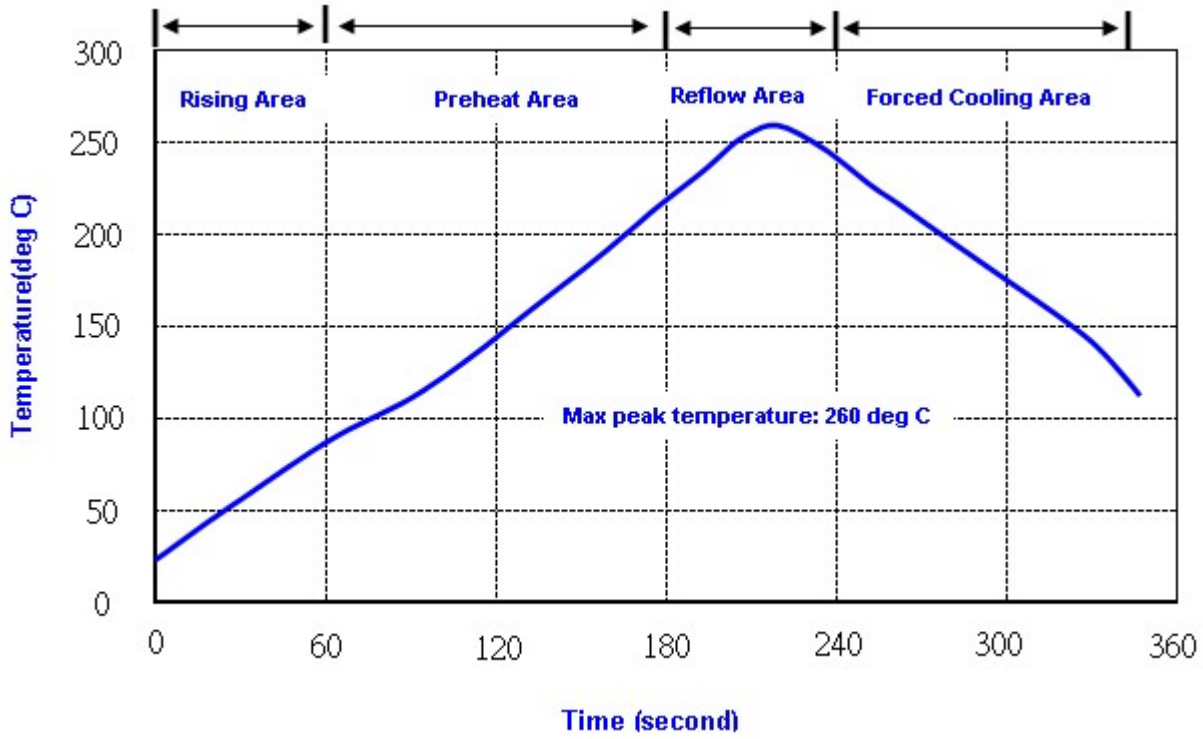
5 10 PITCHES CUMULATIVETOLERANCE +/-0.2mm.

Packing Quantity/Packing:

3K pcs maximum per reel



Reflow Profile:



Note: 1.Max peak temperature: 260+/-5 deg C; Time: 10+/-2 sec
2. Temperature: 217+/-5 deg C; Time: 90~100 sec

Reliability Specifications

Test name	Test process / method	Reference standard
Mechanical characteristics		
resistance to Soldering heat (IR reflow)	Temp./ Duration : 260°C /10sec ×2 times Total time : 4min.(IR-reflow)	EIAJED-4701 -300(301)M(II)
Vibration	Total peak amplitude : 1.5mm Vibration frequency : 10 to 55 Hz Sweep period : 1.0 minute Vibration directions : 3 mutually perpendicular Duration : 2 hr / direc.	MIL-STD 202F method 201A
Mechanical Shock	directions : 3 impacts per axis Acceleration : 3000g's, +20/-0 % Duration : 0.3 ms (total 18 shocks) Waveform : Half-sine	MIL-STD 202F method 213C
Solderability	Solder Temperature:265±5°C Duration time: 5±0.5 seconds.	MIL-STD 883G method 2003
Environmental characteristics		
Thermal Shock	Heat cycle conditions -55 ℃ (30min) ⟷ 125 ℃ (30min) * cycle time : 10 times	MIL-STD 883G method 1010.7
Humidity test	Temperature : 70 ± 2 °C Relative humidity : 90~95% Duration : 96 hours	MIL-STD 202F method 103B
Dry heat (Aging test)	Temperature : 125 ± 2 °C Duration : 168 hours	MIL-STD 883G method 1008.2 condition C
PCT test	Pressure: 2.06kg/cm^2 (2.03*10^5 pa) Temperature : 121 ± 2 °C Relative humidity : 100% Duration : 24 hours	EIAJED-4701-3 B-123A